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Docket No.: ISH-0227
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Toshihiro Tsuchiya

Confirmation No.: 1124

Application No.: 10/523,976

Art Unit: 3723

Filed: February 8, 2005

Examiner: M. T. Rachuba

For: WAFER POLISHING METHOD AND
APPARATUS

RESPONSE TO RESTRICTION REQUIREMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Restriction Requirement dated August 16, 2006(Paper No. 20060810), Applicant elects Group I, claims 1-5, drawn to a method, without traverse.

As a result, Applicants respectfully reserve the right to file a divisional application encompassing the non-elected claims 6-8.

Applicant believes no fee is due with this response. However, if a fee is due, please charge our Deposit Account No. 18-0013, under Order No. ISH-0227 from which the undersigned is authorized to draw.

Dated: September 1, 2006

Respectfully submitted,

By 

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